



PATENT APPLICATION

Attorney Docket No. 99-099
65611 (6653)

2859

Date: May 8, 2001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Rajagopalan, et al.

Application No.: 09/465,131

Filed: December 16, 1999

For: METHOD AND APPARATUS
FOR THERMAL PROFILING
OF FLIP-CHIP PACKAGES

Group Art Unit: 2859

Examiner: Yaritza Guadalupe

Box NON-FEE AMENDMENT
Commissioner for Patents
Washington, D.C. 20231

Sir:

Transmitted herewith is an amendment/reply in the above-identified application.

(X) Amendment A/Reply to the Office Action mailed February 13, 2001.
(X) No additional fee is required.
(X) A Return Receipt Postcard is enclosed.

Fee Calculation For Claims As Amended

	As Amended	Previously Paid For	Present Extra	Rate	Additional Fee
Independent Claims	<u>3</u>	<u>3</u>	<u>*</u> <u>0</u>	<u>x</u> <u>\$ 80.00</u>	<u>=</u> <u>\$ 0</u>
Total Claims	<u>6</u>	<u>11</u>	<u>**</u> <u>0</u>	<u>x</u> <u>\$ 18.00</u>	<u>=</u> <u>\$ 0</u>
Fee for Multiply Dependent Claims				<u>\$ 270.00</u>	<u>\$ 0</u>
* At least 3				Total Additional Fee	<u>\$ 0</u>
** At least 20					

CERTIFICATE OF MAILING
I hereby certify that this paper is being
deposited with the United States Postal Service
as first class mail in an envelope addressed
to: Commissioner for Patents, Washington, D.C.
20231, on this date.

May 8, 2001
Date

Eric James Whitesell
Eric James Whitesell
Registration No. 38,657

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(X) The Commissioner is hereby authorized to charge any additional fees which may be required in this application under 37 C.F.R. §§1.16-1.17 during its entire pendency, or credit any overpayment, to Deposit Account No. 12-2252. Should no proper payment be enclosed herewith, as by a check being in the wrong amount, unsigned, post-dated, otherwise improper or informal or even entirely missing, the Commissioner is authorized to charge the unpaid amount to Deposit Account No. 12-2252. A duplicate copy of this sheet is enclosed.



Eric James Whitesell
Reg. No. 38,657
May 8, 2001

DIRECT ALL CORRESPONDENCE TO:

LSI LOGIC CORPORATION
1551 McCarthy Blvd. MS D-106
Milpitas, CA 95035
(408) 433-8708



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DOCKET NO. 99-099
FETF: 65611

A/A
Catherine
5-17-01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Sarathy Rajagopalan, et al.
Serial No.: 09/465,131
Filed: December 16, 1999
For: METHOD AND APPARATUS FOR
THERMAL PROFILING OF
FLIP-CHIP PACKAGES
Group Art
Unit: 2859
Examiner: Yaritza Guadalupe

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify that this paper is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on this date.

May 8, 2001
Date

Eric James Whitesell
Eric James Whitesell
Reg. No. 38-657

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Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In response to the Office Action mailed February 13, 2001, please amend the subject application as follows: